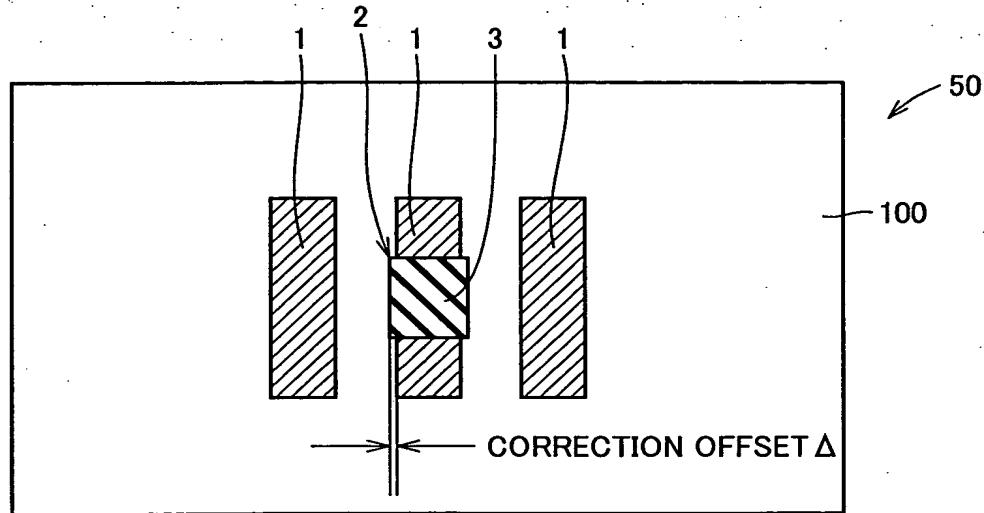


**FIG.1**



**FIG.2**

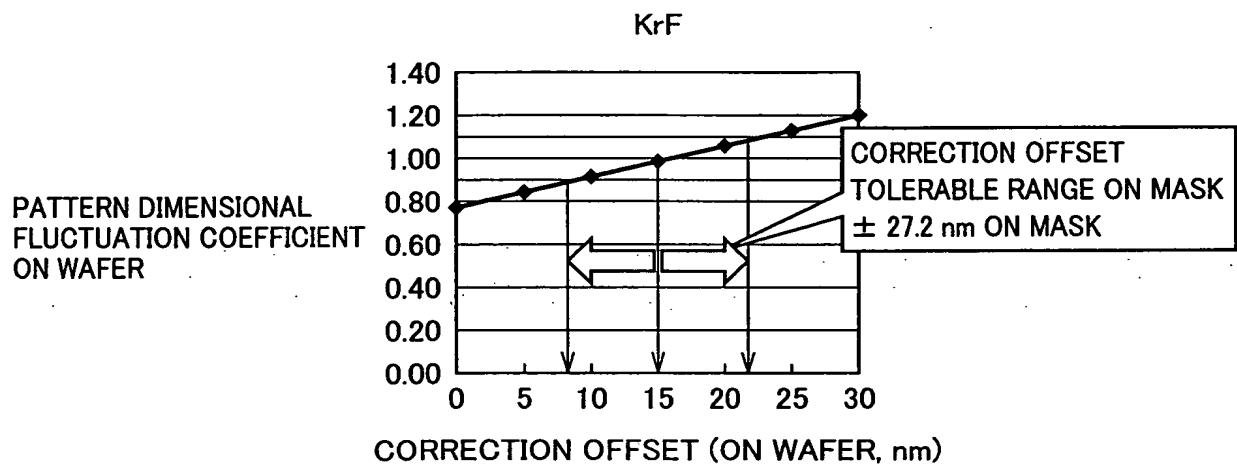


FIG.3

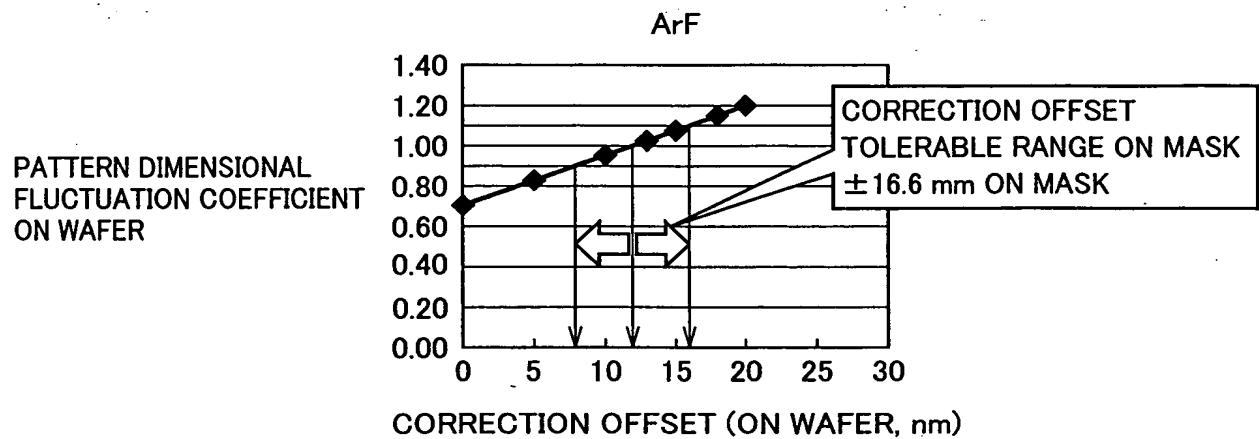
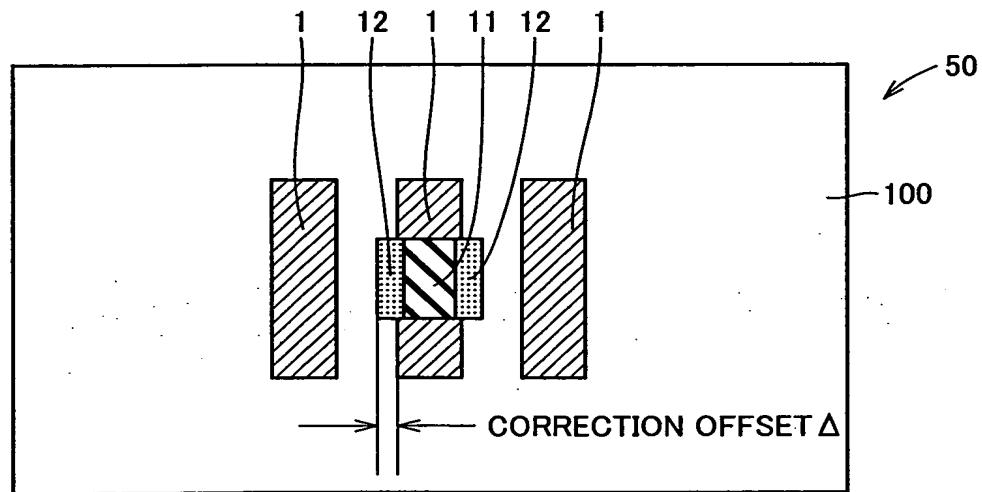
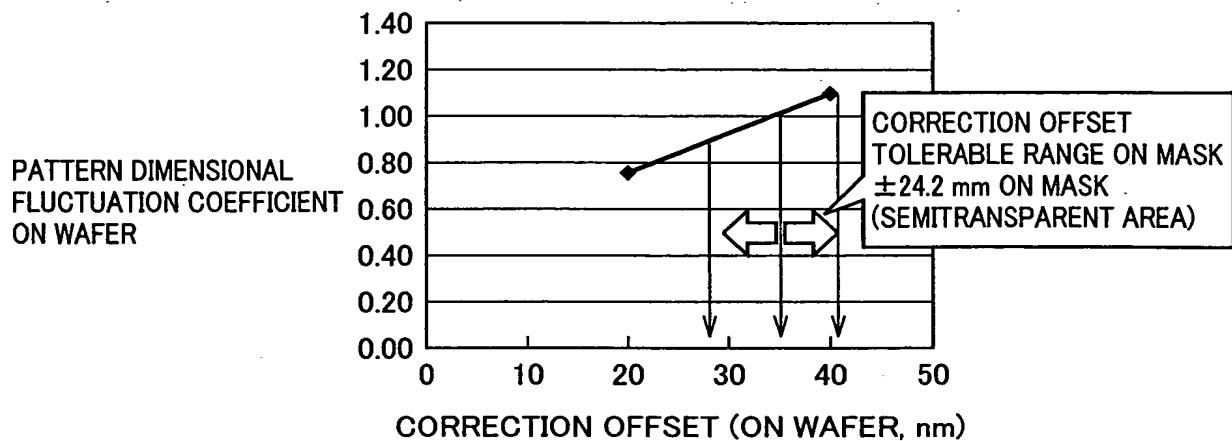


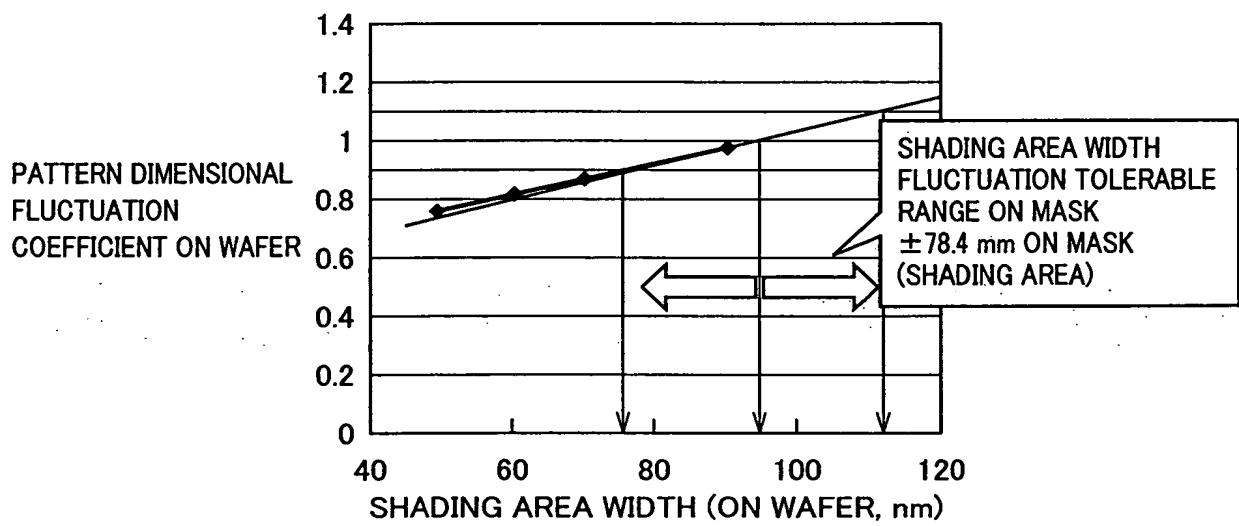
FIG.4



**FIG.5**

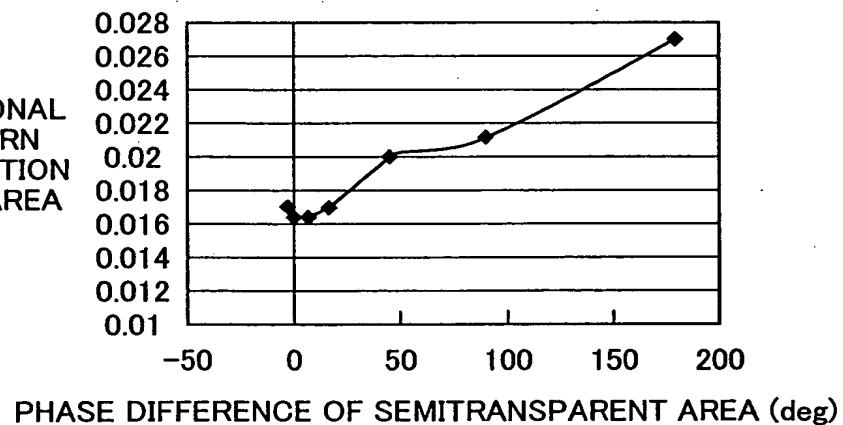


**FIG.6**

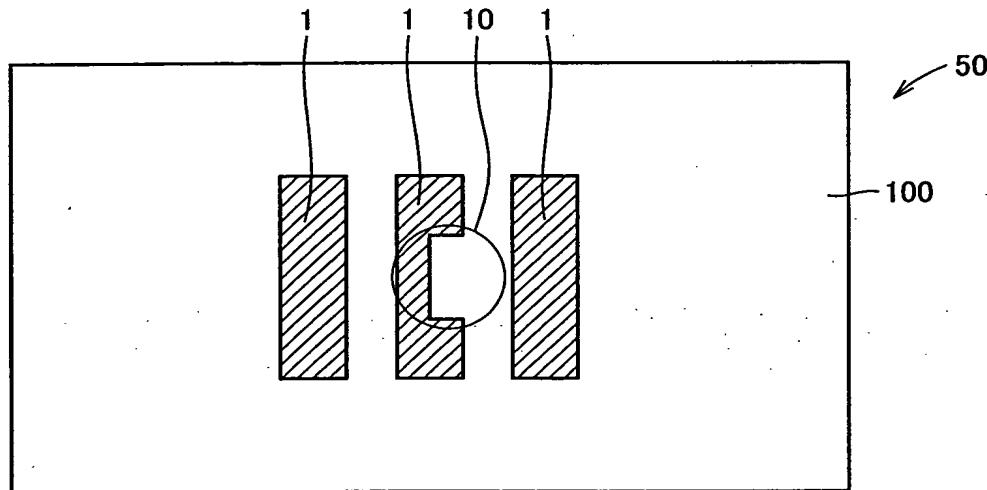


**FIG.7**

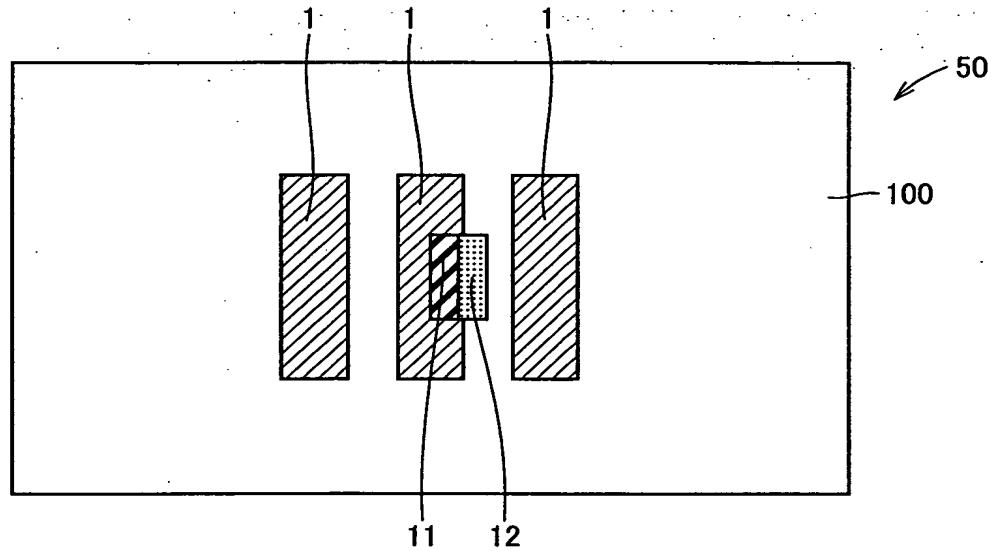
RATIO OF THE DIMENSIONAL FLUCTUATION IN PATTERN ON WAFER TO FLUCTUATION IN SEMITRSPARENT AREA WIDTH



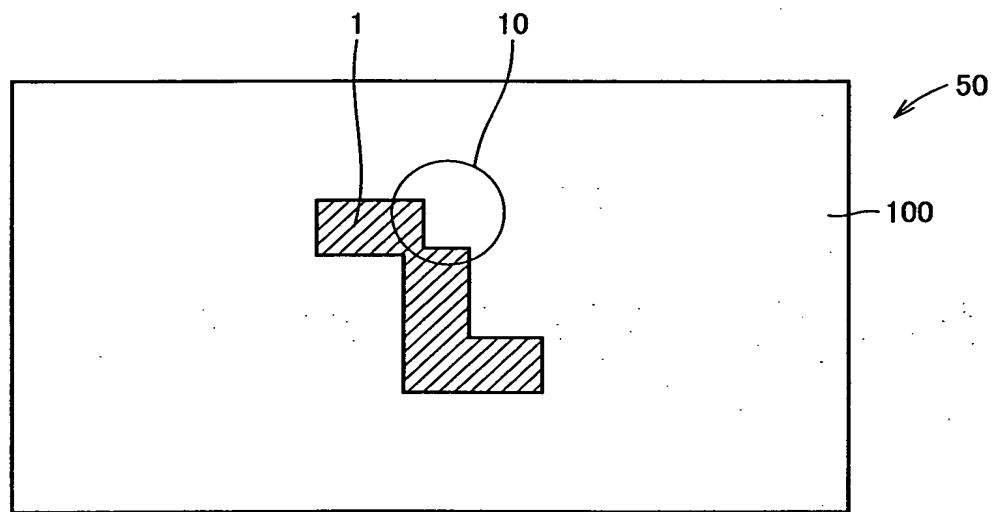
**FIG.8**



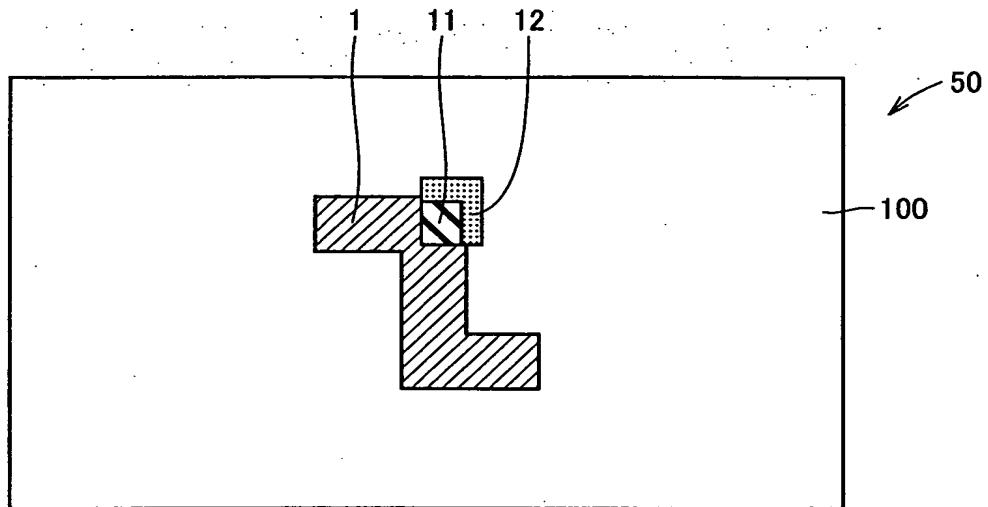
**FIG.9**



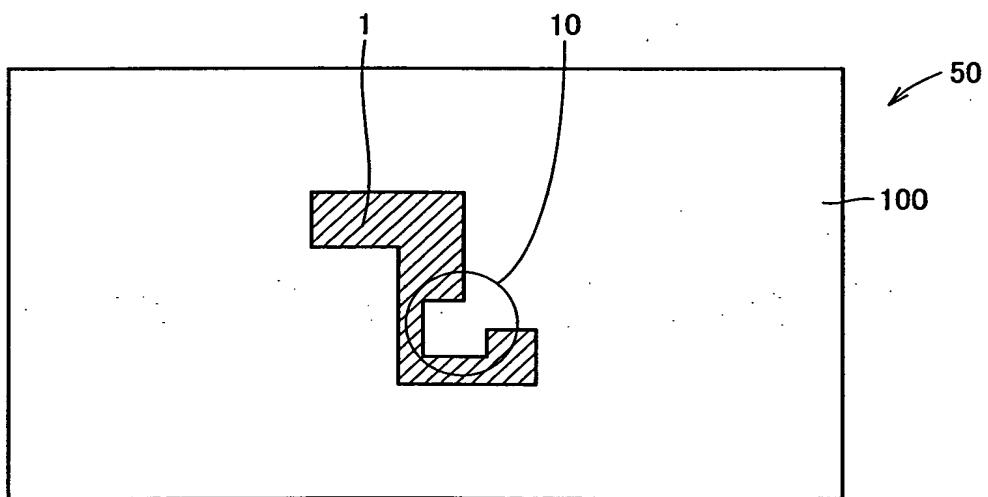
**FIG.10**



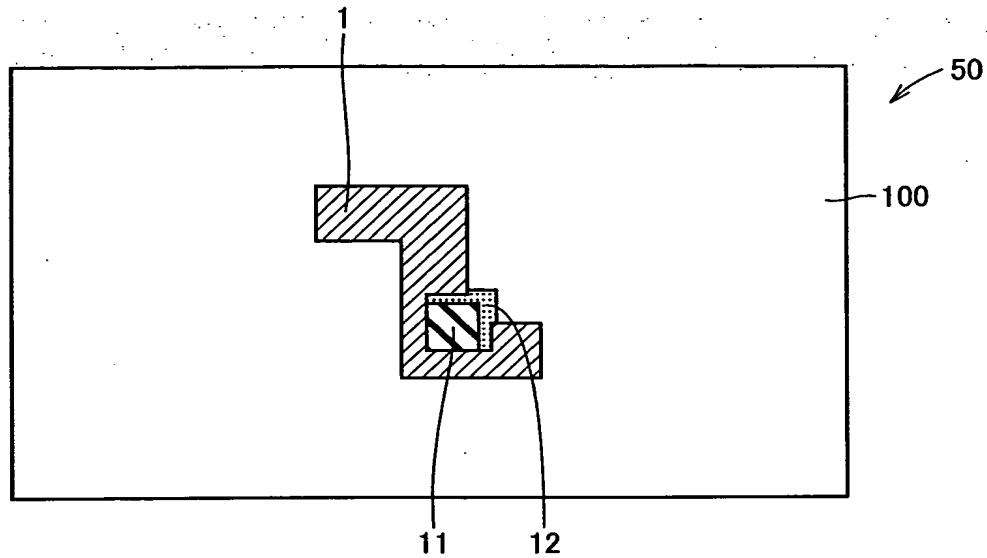
**FIG.11**



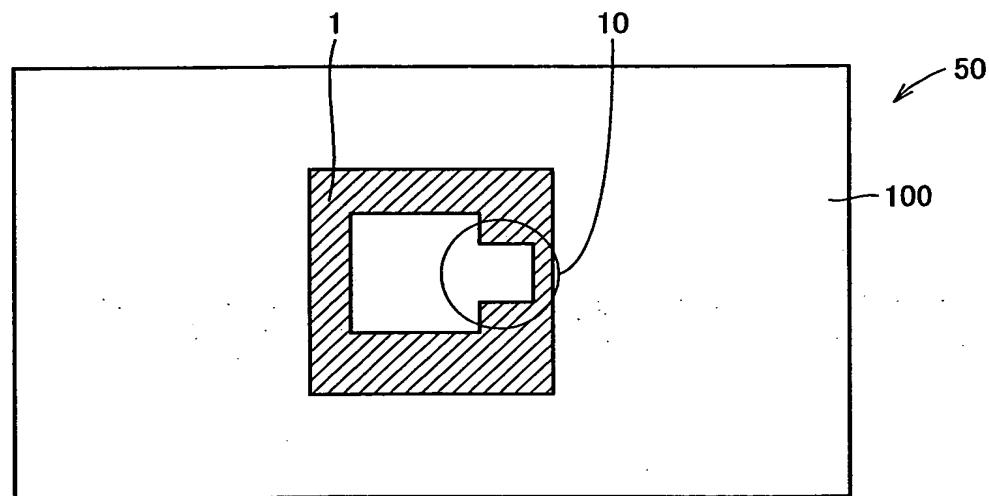
**FIG.12**



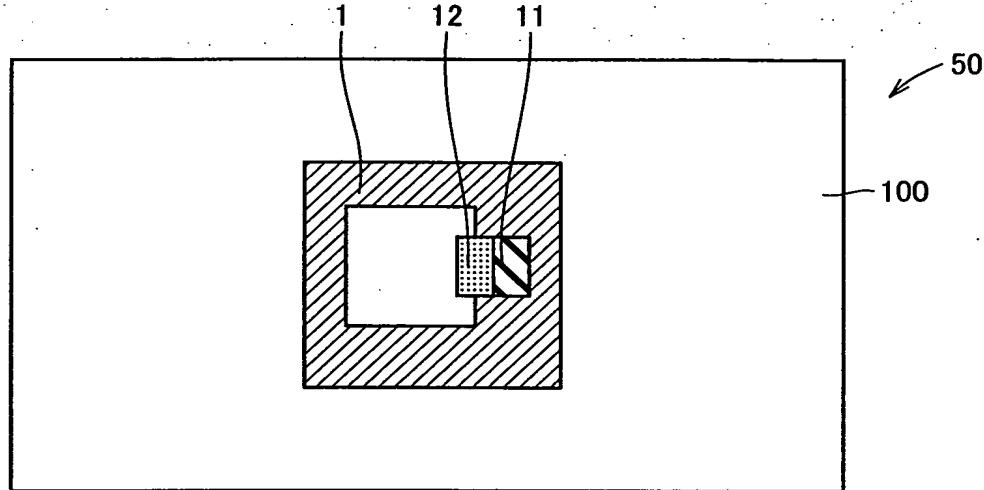
**FIG.13**



**FIG.14**



**FIG.15**



**FIG.16**

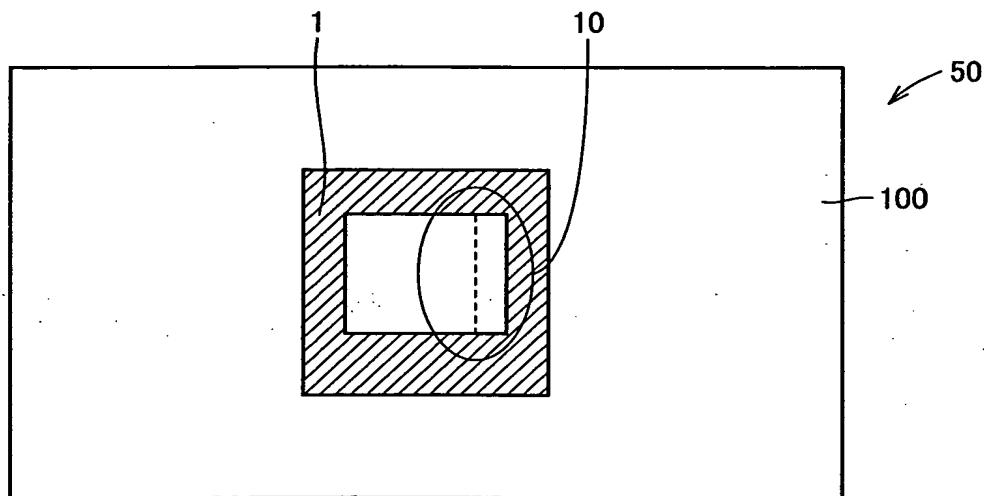


FIG.17

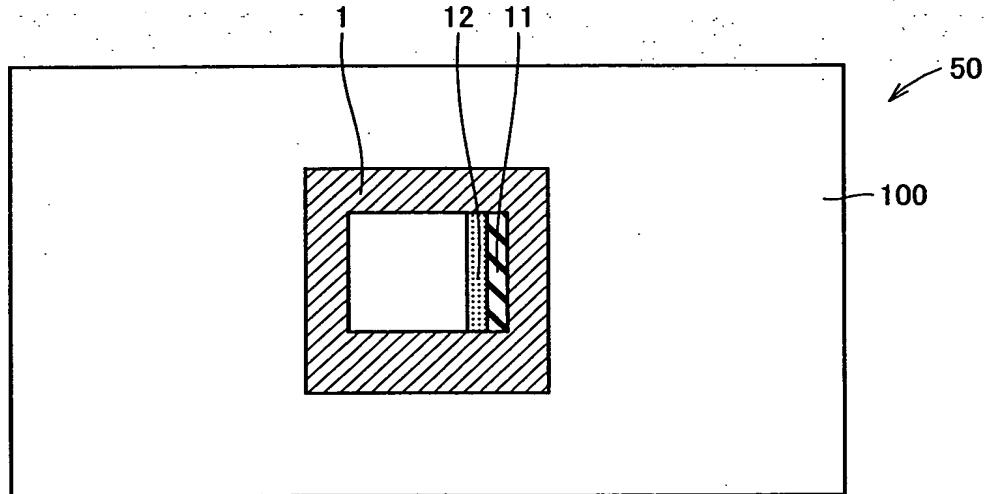
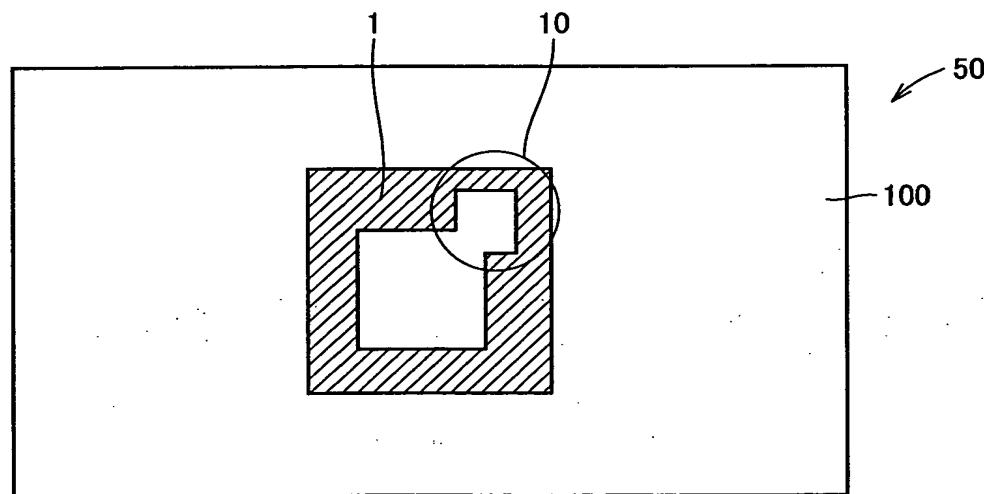
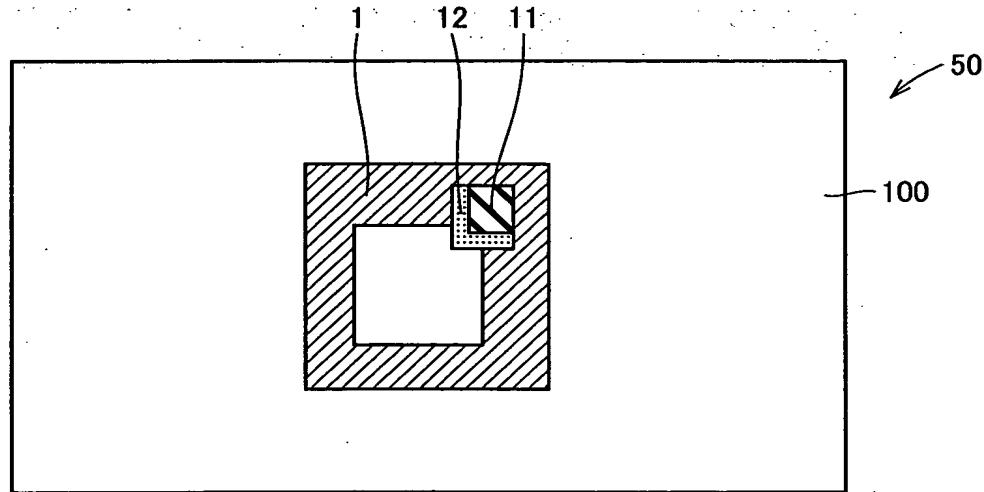


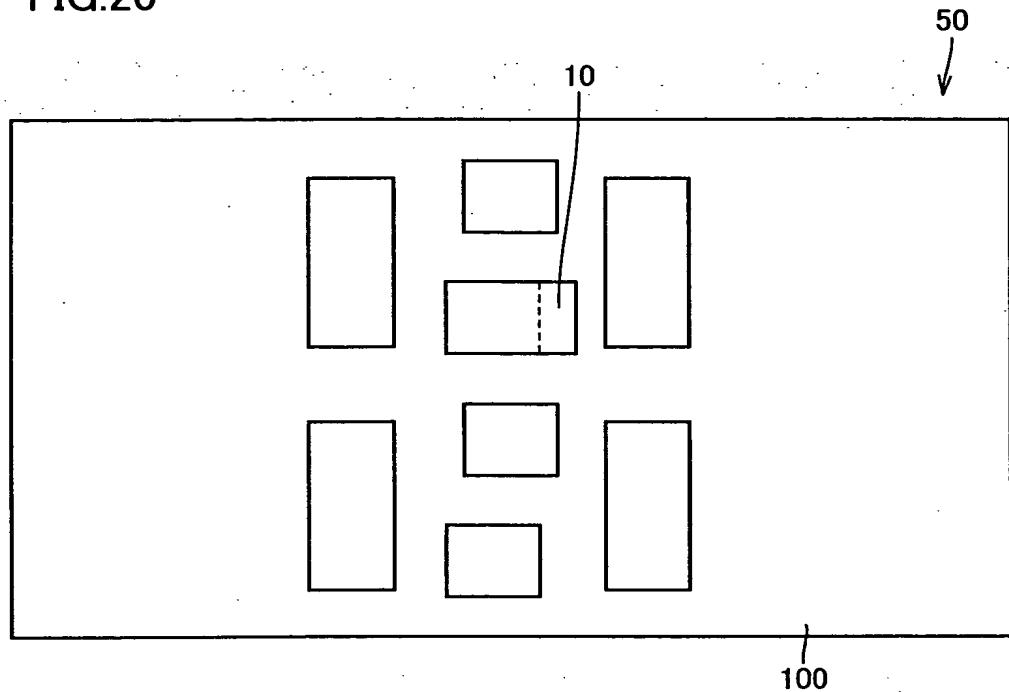
FIG.18



**FIG.19**



**FIG.20**



**FIG.21**

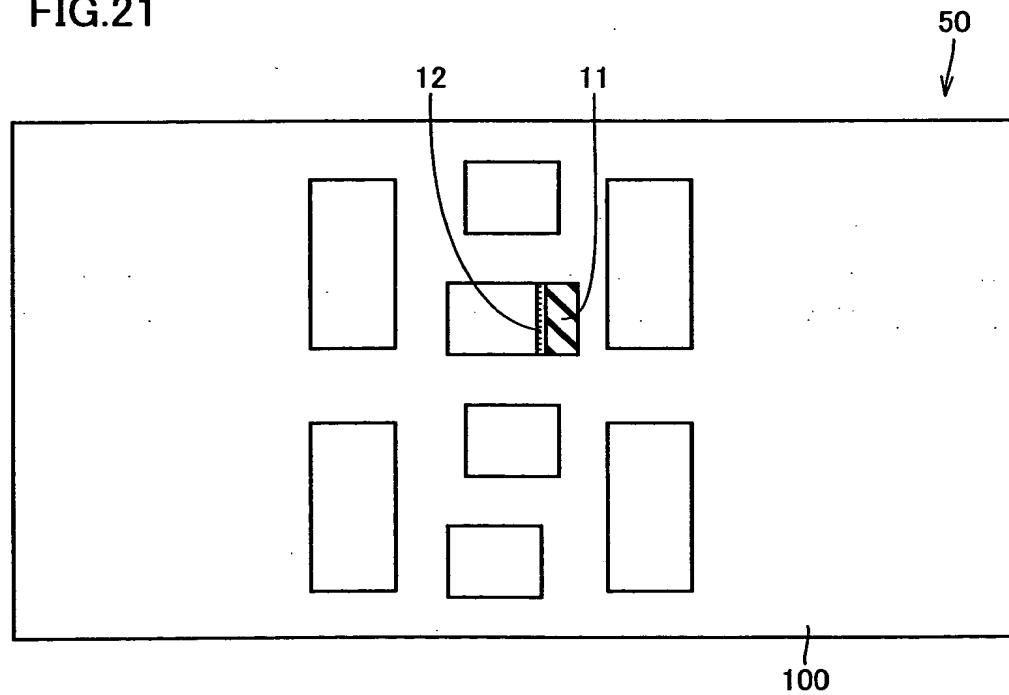
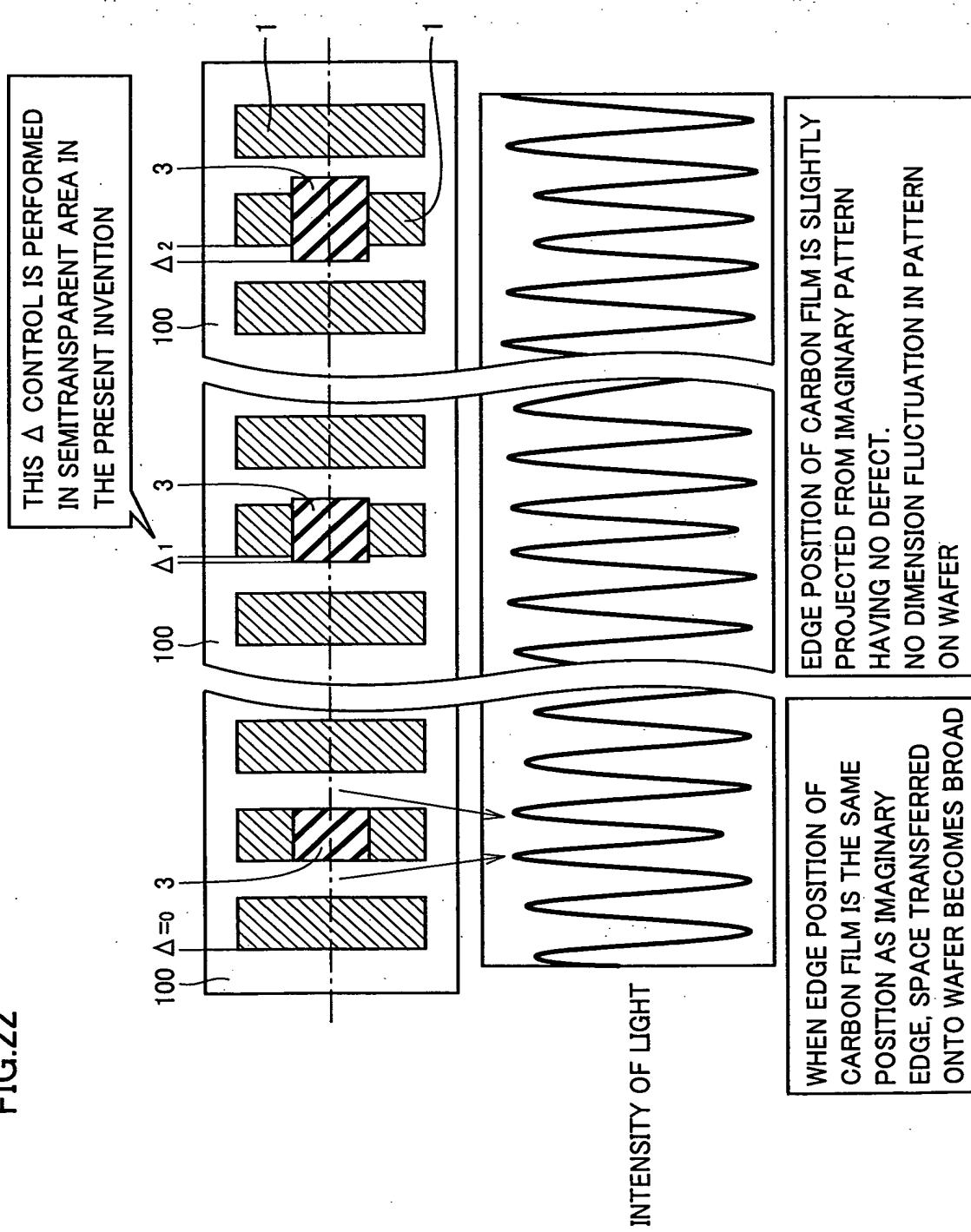
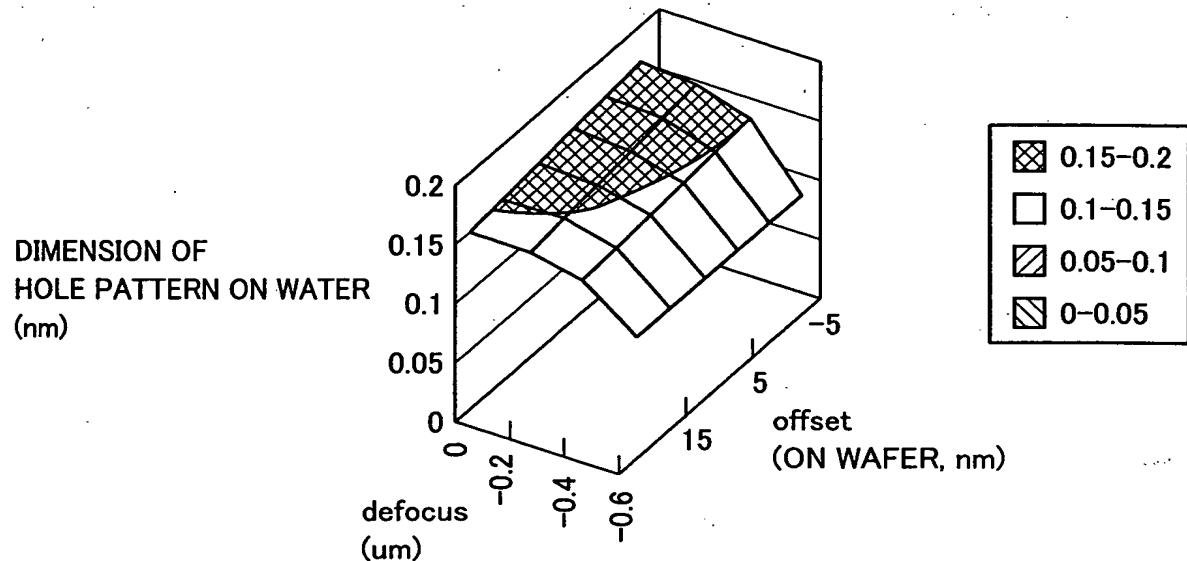


FIG.22



**FIG.23**  
METHOD OF COMPARATIVE EMBODIMENT



**FIG.24**  
METHOD OF THE PRESENT INVENTION

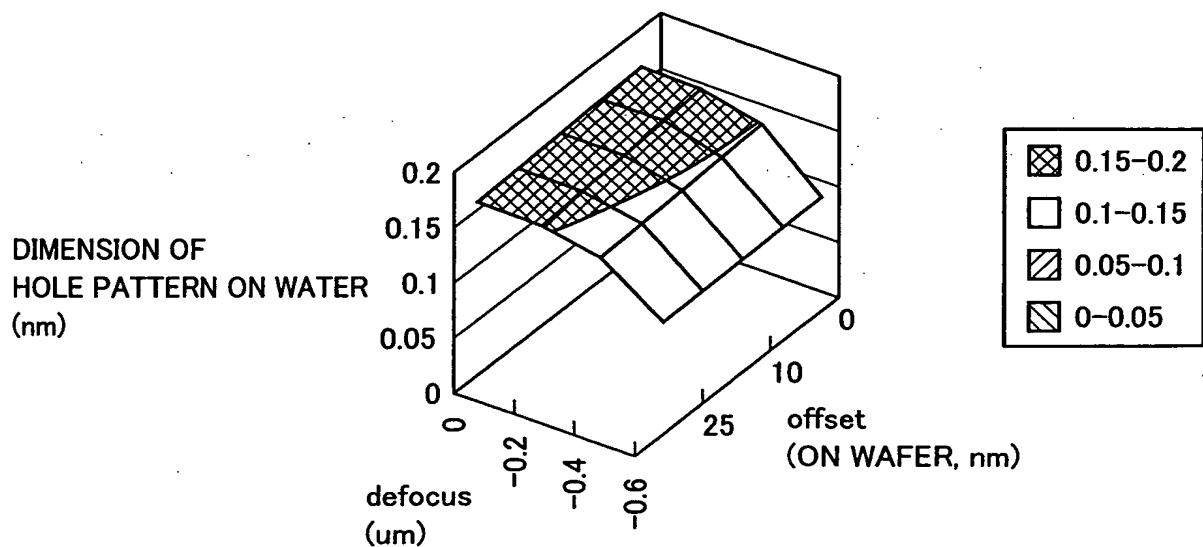


FIG.25

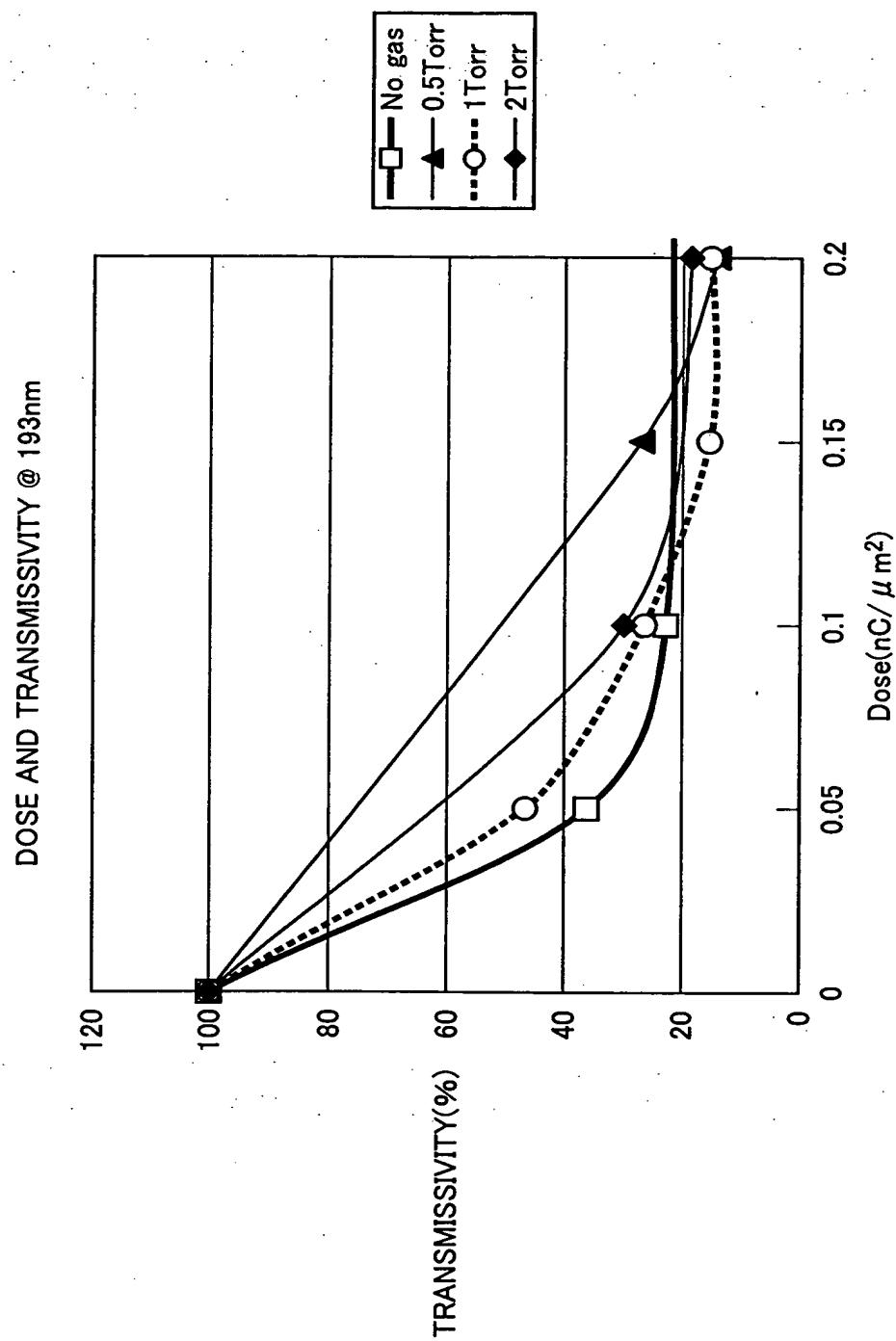


FIG.26

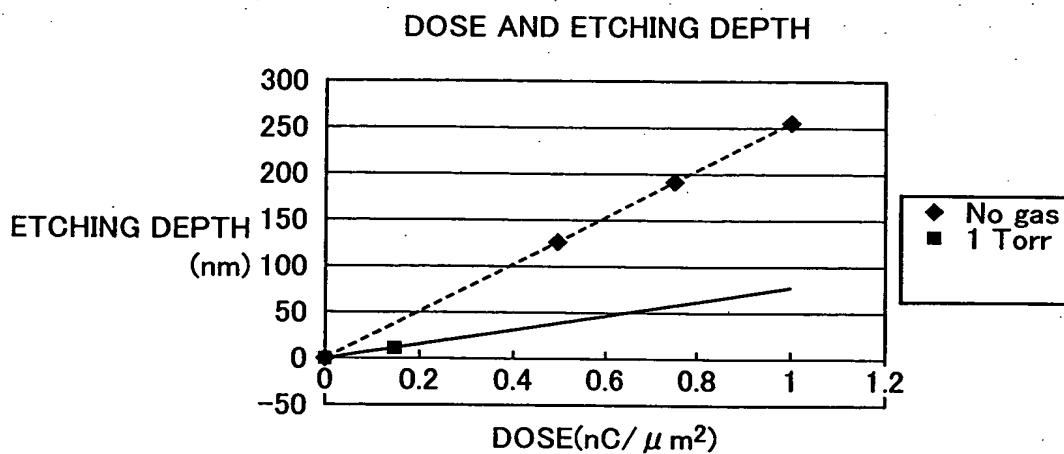
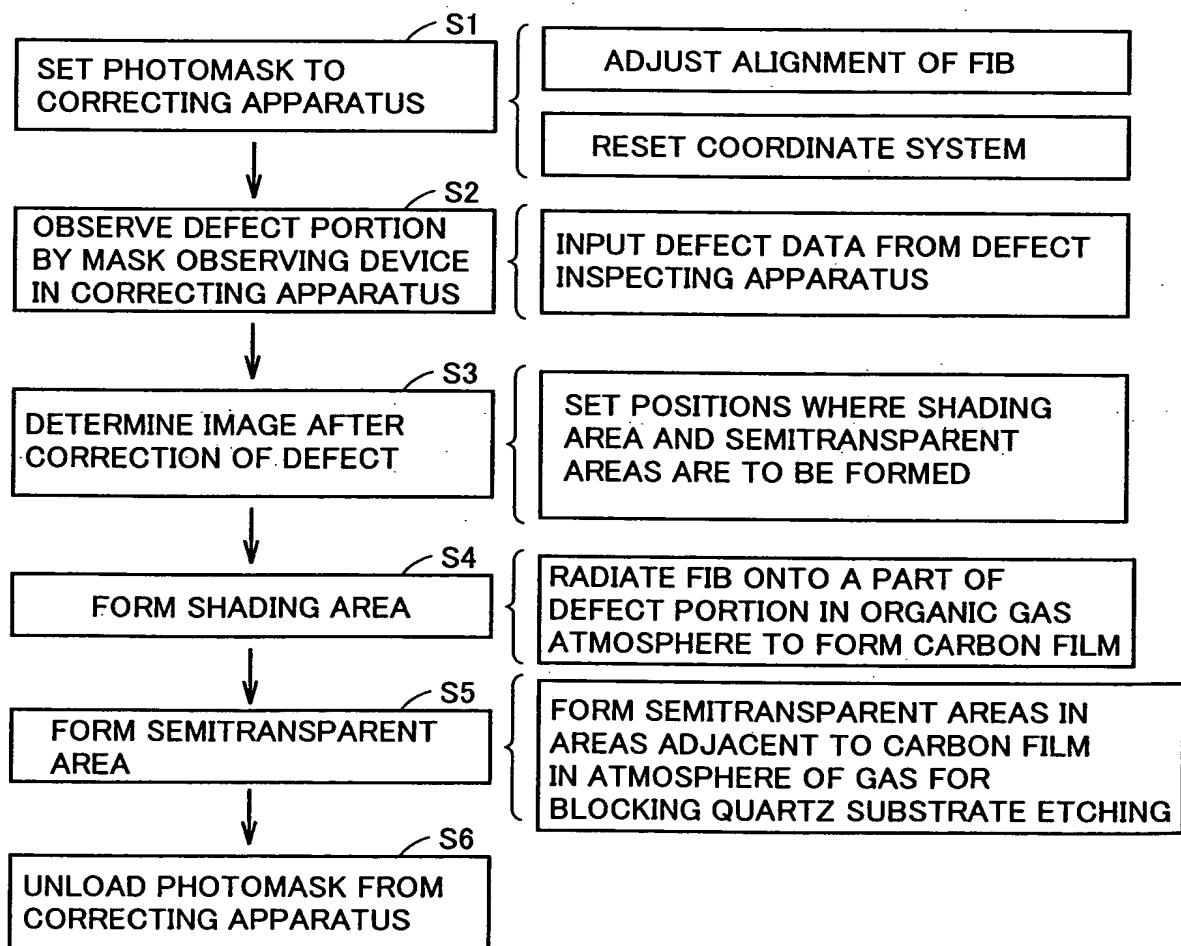
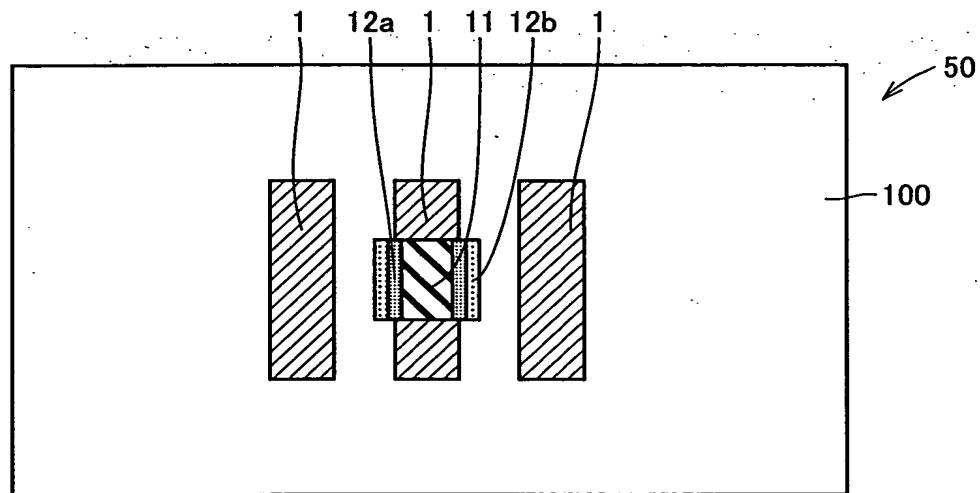


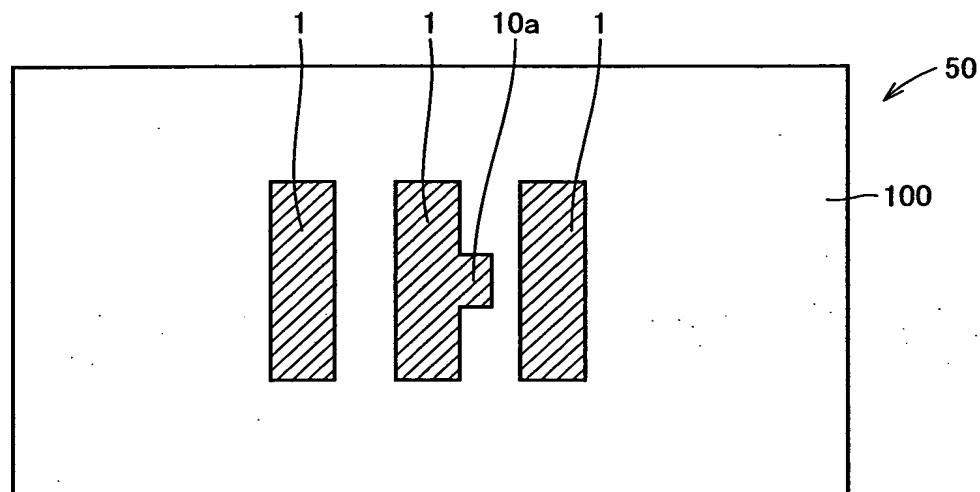
FIG.27



**FIG.28**



**FIG.29**



**FIG.30**

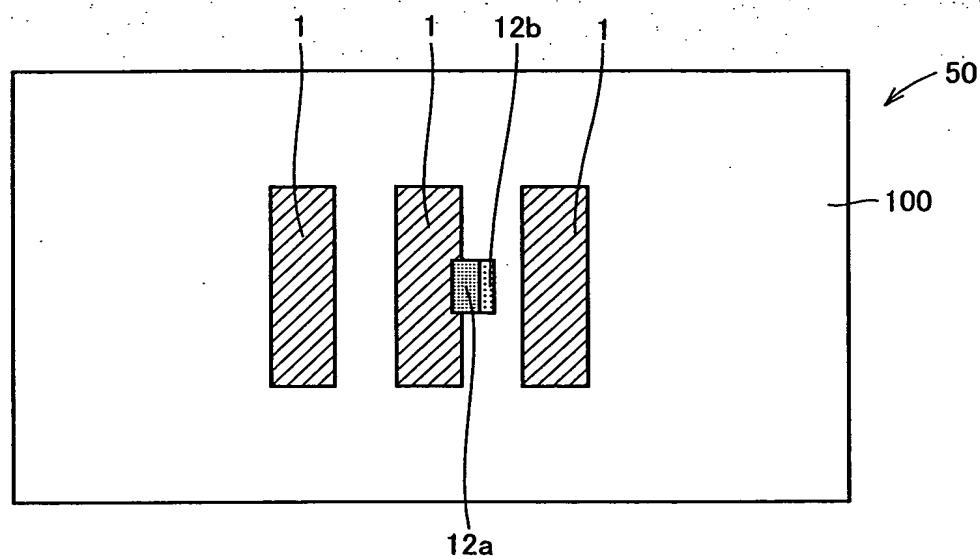


FIG.31

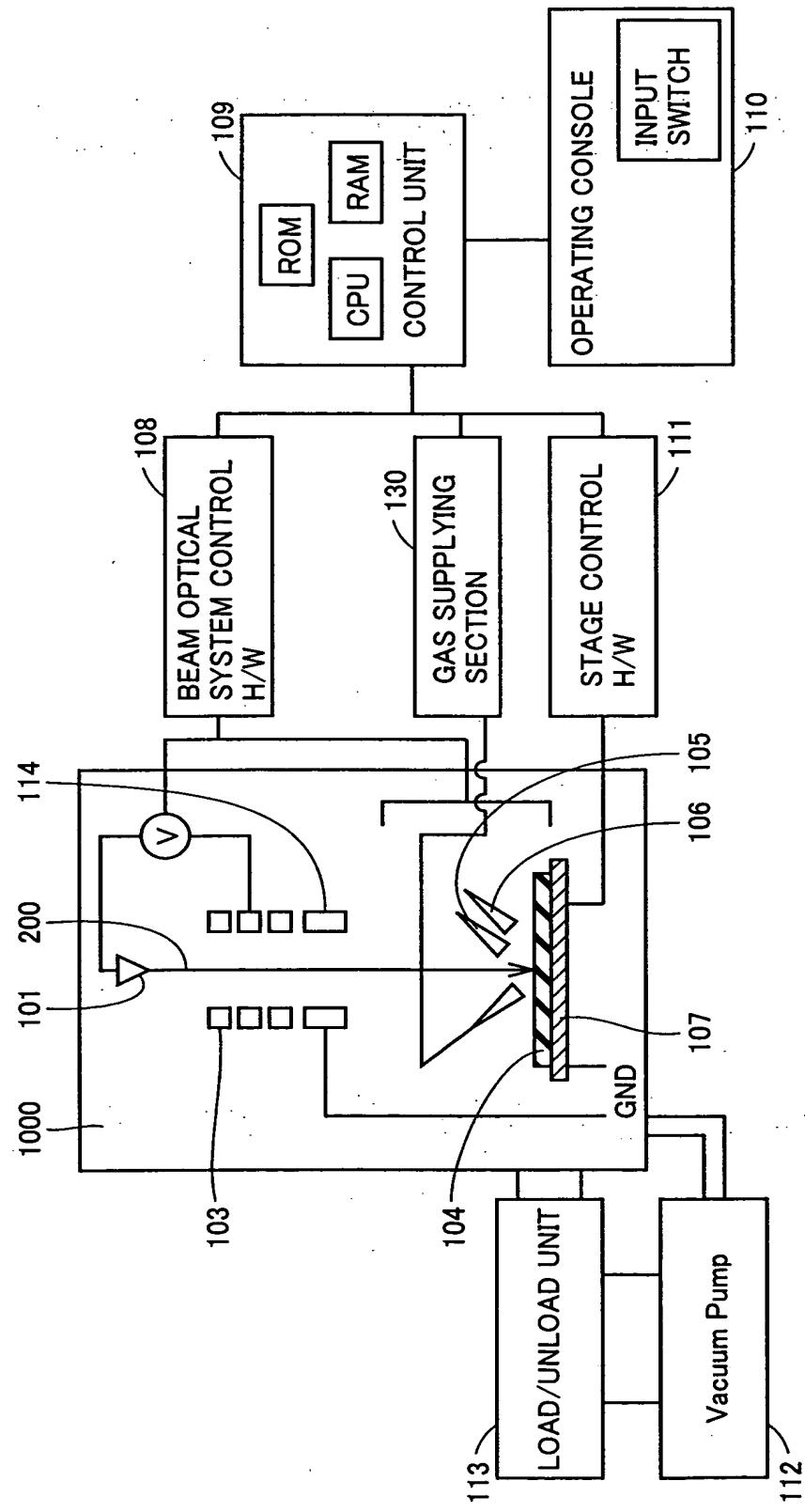


FIG.32

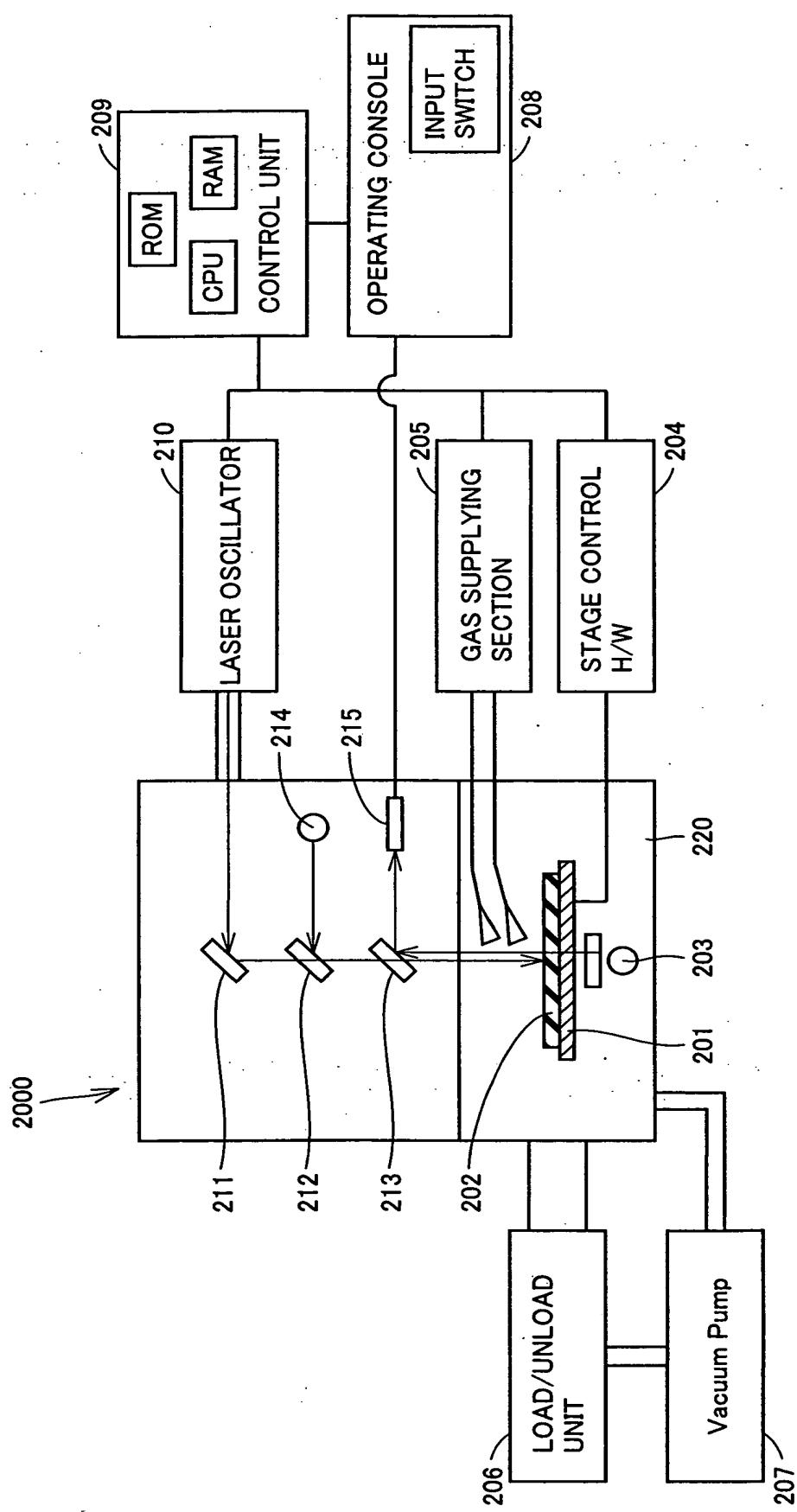
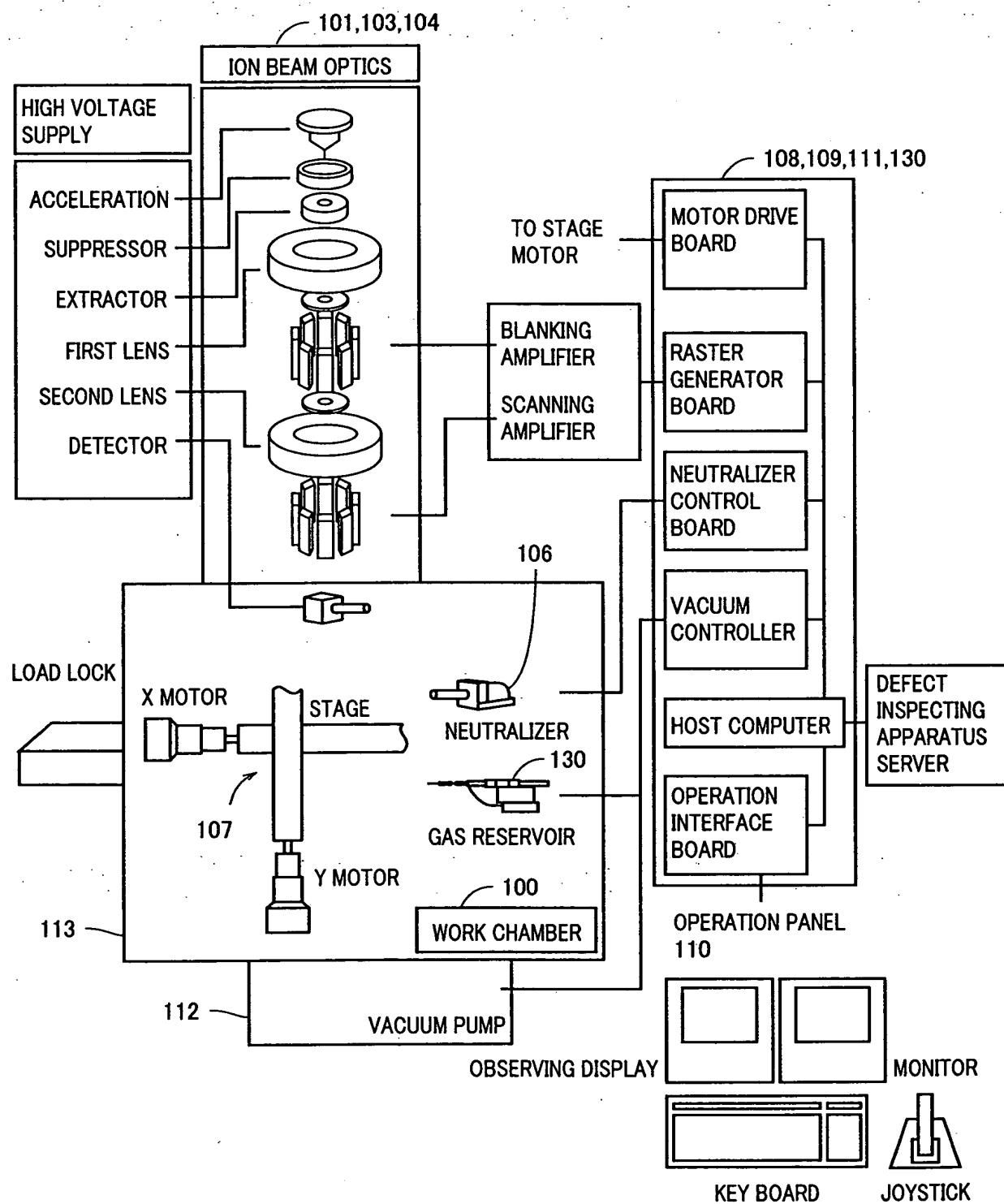
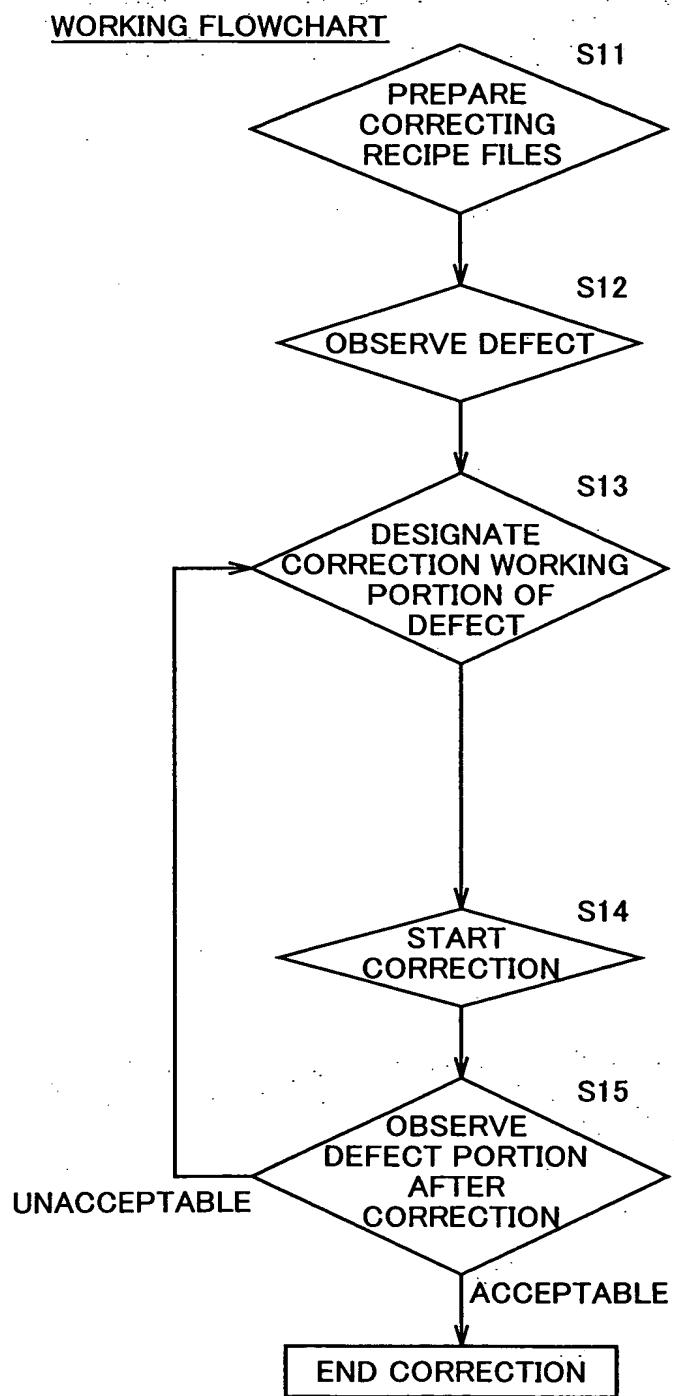


FIG.33



**FIG.34**



**FIG.35**

**FLOWCHART OF MASK DEFECT  
CORRECTING APPARATUS OPERATION**

